



3D Packaging and Integration Global Technical Committee

Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Summer Meeting 2023

June 21, 2023, 13:30-16:00[JST]

OVTCCM

TC Chapter Announcements

Next TC Chapter Meeting

Tuesday, September 5 13:30-15:30

OVTCCM

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI), Haruo Shimamoto (AIST)

SEMI Staff: Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
<i>AIST</i>	<i>Shimamoto</i>	<i>Haruo</i>	Shin-Etsu Polymer Co., Ltd.	Shida	Hiroyuki
<i>AiT</i>	<i>Kato</i>	<i>Kazunori</i>	Shin-Etsu Polymer Co., Ltd.	Odashima	Satoshi
<i>iNEMI</i>	<i>Tsuruya</i>	<i>Masahiro</i>	<i>Panasonic Industrial Devices SUNX Co., Ltd.</i>	<i>SHIEH</i>	<i>YAU DE</i>
<i>KOKUSAI ELECTRIC CORPORATION</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>	SEMI Japan	Nakajo	Mami
Hitachi High-Tech Corporation	Yoshino	Eiji			

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6994	Reapproval of SEMI G89-0211 (Reapproved 0318) Specification for Leadframe Strip Size	Passed as balloted
6995	Reapproval of SEMI G71-0996 (Reapproved 0318) Specification for Barcode Marking of Intermediate Containers for Packaging Materials	Passed as balloted

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6996	Reapproval of SEMI G69-0996 (Reapproved 0318): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds	Passed as balloted
6997	Reapproval of SEMI G90-0811 (Reapproved 0318): Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes	Passed as balloted
6998	Reapproval of SEMI G66-96 (Reapproved 0318): Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic	Passed as balloted
6999	Reapproval of SEMI G23-0996 (Reapproved 0318): Test Method of Inductance for Internal Traces of Semiconductor Packages	Passed as balloted

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&R Action</i>	<i>A&R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 8 Authorized Ballots

<i>#</i>	<i>When</i>	<i>TF</i>	<i>Details</i>
None			

Table 9 SNARF(s) Granted a One-Year Extension

<i>#</i>	<i>TF</i>	<i>Title</i>	<i>Expiration Date</i>
None			

Table 10 SNARF(s) Abolished

<i>#</i>	<i>TF</i>	<i>Title</i>
None		

Table 11 Standard(s) to receive Inactive Status

<i>Standard Designation</i>	<i>Title</i>
None	

Table 12 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230621-01	SEMI Staff	To submit the ballot review sheets to the A&R

Table 13 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230315-01	3D Packaging & Integration Steering Group	To call for new members to restart the activities of 3DP&I Steering Group to 3DP&I, Traceability and PIC Japan TC members.

1 Welcome, Reminders, and Introductions

Kato Kazunori (AiT) called the meeting to order at 1330. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01-02_Required Element Nov 2022_E+J (new template),

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Haruo Shimamoto (AIST-National Institute of Advanced Industrial and Technology)

By / 2nd: Mitsuhiro Matsuda (KOKUSAI ELECTRIC CORPORATION)

Discussion: None

Vote: 6 in favor and 0 opposed. Motion passed.

Attachment: 20230315_3DPI-Japan_MeetingMinutes_final ,

3 Liaison Reports

3.1 3D Packaging & Integration North America TC Chapter

Mami Nakajo (SEMI Japan) reported for the 3D Packaging & Integration North America TC Chapter activity status based on the report as attached.:

Attachment: NA 3DP&I Liaison Report Apr2023 v1,

3.2 3D Packaging & Integration Taiwan TC Chapter

Mami Nakajo (SEMI Japan) reported for the 3D Packaging & Integration Taiwan TC Chapter activity status based on the report as attached.:

Attachment: 3D P&I TW Liaison Report_20220902_v1,

3.3 SEMI Staff Report

Mami Nakajo (SEMI) explained the SEMI Staff Report based on the report as attached.:



Attachment: Staff Report July 2023 v1,

Haruo Shimamoto(AIST) took over the chair.

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Cycle 2-2023 submitted by the Japan TC Chapter

4.1.1 Document # 6994 - Reapproval of SEMI G89-0211 (Reapproved 0318) Specification for Leadframe Strip Size

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

Attachment: 6994_Ballot Report_final,

4.1.2 Document # 6995 -Reapproval of SEMI G71-0996 (Reapproved 0318) Specification for Barcode Marking of Intermediate Containers for Packaging Materials

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

Attachment: 6995_Ballot Report_final,

4.1.3 Document #6996 -Reapproval of SEMI G69-0996 (Reapproved 0318): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

Attachment: 6996_Ballot Report_final,

4.1.4 Document #6997 -Reapproval of SEMI G90-0811 (Reapproved 0318): Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

Attachment: 6997_Ballot Report_final,

4.1.5 Document #6998 -Reapproval of SEMI G66-96 (Reapproved 0318):Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

Attachment: 6998_Ballot Report_final

4.1.6 Document #6999 -Reapproval of SEMI G23-0996 (Reapproved 0318): Test Method of Inductance for Internal Traces of Semiconductor Packages

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

Attachment: 6999_Ballot Report_final,

Action Item: 20230621-01 (SEMI Staff) To submit the ballot review sheets to the A&R

Kato Kazunori (AiT) took over the chair.

5 Subcommittee and Task Force Reports

5.1 GCS Report

Mami Nakajo (SEMI) reported for the GCS.

GCS authorized the below New SNARF for Document Number and for letter ballots in cycle 5-2023.

- Revision to SEMI 3D3-0613 (Reapproved 1218), Guide for Multiwafer Transport and Storage Containers for 300 mm, Thin Silicon Wafers on Tape Frames
- Revision to SEMI 3D4-0915 (Reapproved 0222), Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks
- Revision to SEMI 3D5-0314 (Reapproved 1218), Guide for Metrology Techniques to be Used in Measurement of Geometrical Parameters of Through-Silicon Vias (TSVs) in 3DS-IC Structures
- Revision to SEMI 3D17-1217, Specification for Reference Material for Bonded Wafer Stack Void Metrology

5.2 3D Packaging & Integration 5 Year Review Task Force >

Masahiro Tsuruya (iNEMI) reported the the 3D Packaging & Integration 5 Year Review Task Force status as attached.

Attachment: TF Report - 5yrs Review TF v2023_6,

5.3 3DS IC Bonded Layer Inspection Metrology Task Force

Haruo Shimamoto(AIST) reported for the DS IC Bonded Layer Inspection Metrology Task Force. The TF is currently working on the issues regarding Alignment mark.

5.4 Panel Level Packaging (PLP) Glass Carrier Task Force

No update.

5.5 Steering Working Group

Masahiro Tsuruya (iNEMI) reported the the 3D Packaging & Integration 5 Year Review Task Force status as attached.

Attachment: TF Report - Steering WG v2023_6,

6 Old Business

6.1 Project Period Review-

None

6.2 5 Year Review Check

None



7 New Business

7.1 Proposal of New Activity

None

8 Next Meeting and Adjournment

The next meeting is scheduled for Tuesday, September 5, 2023, 13:30-15:30[JST] @OVTCCM

See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: [15:30]>.

Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

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Email: mnakajo@semi.org

Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	June 29,2023
Masahiro Tsuriya (iNEMI), Co-chair	September 2, 2023
Haruo Shimamoto(AIST), Co-chair	June 29, 2023

Table 14 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
01-02_Required Element Nov 2022_E+J (new template)	6996_Ballot Report_final
20230315_3DPI-Japan_MeetingMinutes_final	6997_Ballot Report_final
NA 3DP&I Liaison Report Apr2023 v1	6998_Ballot Report_final
3D P&I TW Liaison Report_20220902_v1	6999_Ballot Report_final
Staff Report July 2023 v1	TF Report - 5yrs Review TF v2023_6
6994_Ballot Report_final	TF Report - Steering WG v2023_6
6995_Ballot Report_final	

Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.